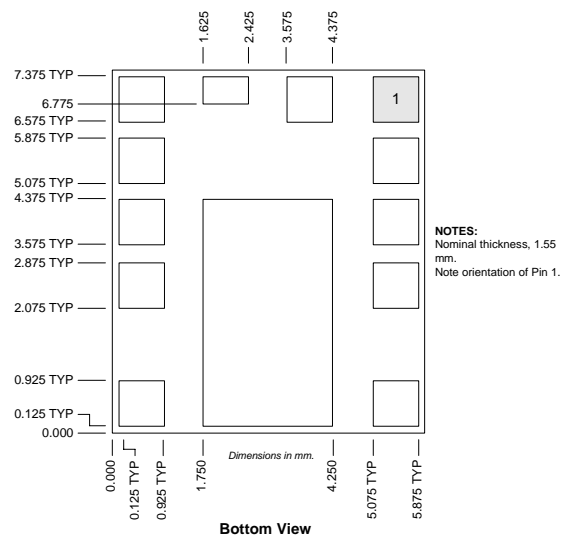


Typical Applications

- 3V CDMA US-PCS Handsets
- 3V CDMA2000/1X PCS Handsets
- Spread-Spectrum Systems
- Designed for Compatibility with Qualcomm Chipsets

Product Description

The RF3300-3 is a high-power, high-efficiency linear amplifier IC targeting 3V handheld systems. The device is manufactured on an advanced Gallium Arsenide Hetero-junction Bipolar Transistor (HBT) process, and has been designed for use as the final RF amplifier in dual-mode 3V CDMA handheld digital cellular equipment, spread-spectrum systems, and other applications in the 1850MHz to 1910MHz band. The RF3300-3 has a digital control line for low power application to reduce the current drain. The device is self-contained with 50Ω input and output that is matched to obtain optimum power, efficiency, and linearity characteristics. This amplifier contains a temperature compensating bias circuit for improved performance over temperature.



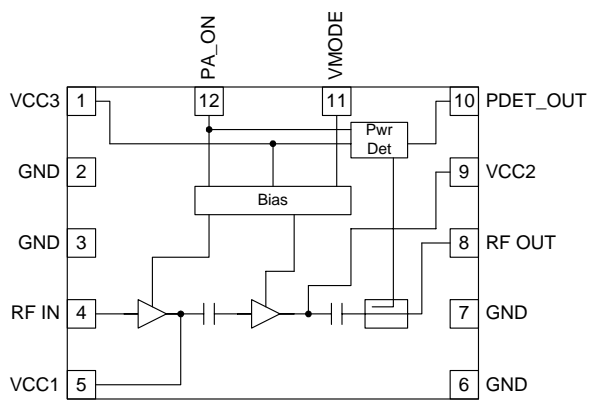
Optimum Technology Matching® Applied

- | | | |
|-------------------------------------|----------------------------------------------|--------------------------------------------------|
| <input type="checkbox"/> Si BJT | <input checked="" type="checkbox"/> GaAs HBT | <input type="checkbox"/> GaAs MESFET |
| <input type="checkbox"/> Si Bi-CMOS | <input type="checkbox"/> SiGe HBT | <input type="checkbox"/> Si CMOS |
| <input type="checkbox"/> InGaP/HBT | <input type="checkbox"/> GaN HEMT | <input checked="" type="checkbox"/> SiGe Bi-CMOS |

Package Style: Module (6mmx7.5mm)

Features

- Single 3V Supply with Internal V_{REF}
- Integrated Power Detector
- 25dB Linear Gain
- 40mA Idle Current (Low Power Mode)
- Temperature Compensating Bias Circuit
- Integrated PA Enable Switch



Functional Block Diagram

Ordering Information

RF3300-3 3V 1900MHz Linear Amplifier Module
 RF3300-3 PCBA Fully Assembled Evaluation Board

RF Micro Devices, Inc.
 7628 Thorndike Road
 Greensboro, NC 27409, USA

Tel (336) 664 1233
 Fax (336) 664 0454
<http://www.rfmd.com>

RF3300-3

Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage (RF off)	+8.0	V _{DC}
Supply Voltage (P _{OUT} ≤28dBm)	+5.2	V _{DC}
Control Voltage (PA_ON)	+3.6	V _{DC}
Mode Voltage (V _{MODE})	+3.6	V _{DC}
Input RF Power	+10	dBm
Operating Case Temperature	-30 to +100	°C
Storage Temperature	-30 to +150	°C



Caution! ESD sensitive device.

RF Micro Devices believes the furnished information is correct and accurate at the time of this printing. However, RF Micro Devices reserves the right to make changes to its products without notice. RF Micro Devices does not assume responsibility for the use of the described product(s).

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
High Power State (V _{MODE} Low)					Typical Performance at V _{CC} =3.2V, PA_ON=High, T _{AMB} =25°C, Frequency=1850MHz to 1910MHz (unless otherwise specified)
Frequency Range	1850		1910	MHz	
Linear Gain	24	25		dB	
Second Harmonic		-45		dBc	
Third Harmonic		-45		dBc	
Maximum Linear Output Power (CDMA Modulation)	28			dBm	
Total Linear Efficiency		35		%	P _{OUT} =28dBm
Adjacent Channel Power Rejection		-47	-46	dBc	ACPR @ 1.25MHz, P _{OUT} =28 dBm
		-61	-58	dBc	ACPR @ 2.25MHz, P _{OUT} =28 dBm
Input VSWR		1.5:1			
Output VSWR			10:1		No damage.
Noise Power		-141	6:1	dBm/Hz	No oscillations. >-70dBc At 80MHz offset.
Low Power State (V _{MODE} High)					Typical Performance at V _{CC} =3.2V, PA_ON=High, T _{AMB} =25°C, Frequency=1850MHz to 1910MHz (unless otherwise specified)
Frequency Range	1850		1910	MHz	
Linear Gain	17	20		dB	
Second Harmonic		-45		dBc	
Third Harmonic		-45		dBc	
Maximum Linear Output Power (CDMA Modulation)	16			dBm	
Adjacent Channel Power Rejection		-49	-47	dBc	ACPR @ 1.25MHz, P _{OUT} =16 dBm
		-64	-59	dBc	ACPR @ 2.25MHz, P _{OUT} =16 dBm
Input VSWR		2:1			
Output VSWR			10:1		No damage.
			6:1		No oscillations. >-70dBc

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
DC Supply					$T_{AMB}=25^{\circ}C$
Supply Voltage	3.2	3.7	4.2	V	
Quiescent Current		150	180	mA	$V_{MODE}=Low$
		40	55	mA	$V_{MODE}=High$
PA_ON Current		0.1		μA	
V_{MODE} Current		0.1		μA	
Turn On/Off Time			<40	μs	PA_ON switched from low to high, I_{CC} to within 90% of the final value, P_{OUT} within 1 dB of the final value.
Total Current (Power Down)		5		μA	PA_ON=Low
PA_ON "Low" Voltage Range	0		0.5	V	
PA_ON "High" Voltage Range	1.7	2.7	3.6	V	Must not exceed V_{CC} .
V_{MODE} "Low" Voltage Range	0		0.5	V	
V_{MODE} "High" Voltage Range	1.7	2.7	3.6	V	Must not exceed V_{CC} .
Gain Settling Time			6	μs	PA_ON switched from low to high, P_{OUT} within 1 dB of the final value.
			6	μs	PA_ON switched from high to low, P_{OUT} within 1 dB of the final value.
Internal Power Detector					
PDET Output Voltage		1.35		V	$P_{OUT}=28dBm, V_{MODE}=Low$
		0.6		V	$P_{OUT}=16dBm, V_{MODE}=High$

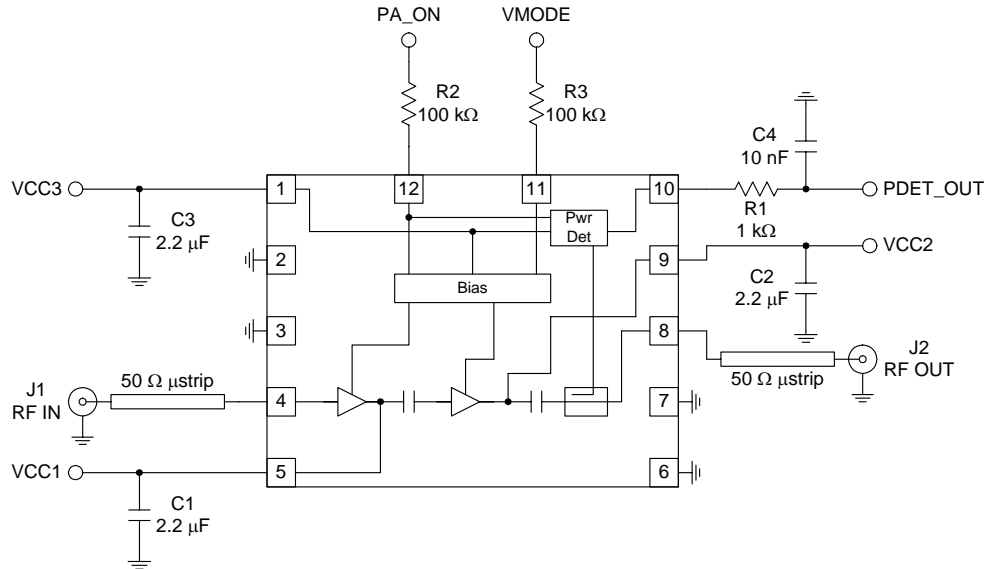
RF3300-3

Pin	Function	Description	Interface Schematic
1	VCC3	Bias circuit and HDET power supply. A low frequency decoupling capacitor (2.2 μ F) is required. Type: P	
2	GND	Ground connection. Connect to the GND_SLUG pin. For best performance, keep traces physically short and connect immediately to ground plane. Type: P	
3	GND	Ground connection. Connect to the GND_SLUG pin. For best performance, keep traces physically short and connect immediately to ground plane. Type: P	
4	RF IN	RF input internally matched to 50 Ω . This input is internally AC-coupled at the IC; however a shunt inductor used in the input matching network will provide a DC path to ground for components connected to the RF IN pin. A DC blocking capacitor may be required at this pin. Type: A, I	<p>The schematic shows the RF IN pin connected to a series capacitor. Following the capacitor is a shunt inductor connected to ground. The signal path continues to the base of a transistor. A DC bias is applied to the base through a capacitor connected to a VCC1 supply. The emitter of the transistor is connected to ground. The collector is connected to the output of the stage.</p>
5	VCC1	First stage power supply. A low frequency decoupling capacitor (2.2 μ F) is required. Type: P	
6	GND	Ground connection. Connect to the GND_SLUG pin. For best performance, keep traces physically short and connect immediately to ground plane. Type: P	
7	GND	Ground connection. Connect to the GND_SLUG pin. For best performance, keep traces physically short and connect immediately to ground plane. Type: P	
8	RF OUT	RF output internally matched to 50 Ω . This input is internally AC-coupled. Type: A, O	
9	VCC2	Output stage power supply. A low frequency decoupling capacitor (2.2 μ F) is required. Type: P	
10	PDET_OUT	Power detector output. Type: A, O	
11	VMODE	Gain step control. When this pin is High, the module is in low power mode, and the amplifier's current is reduced. When this pin is Low, the module is in high power mode. Voltage should not be applied to this pin before VCC3 is applied. Type: D, I	
12	PA_ON	Device enable control. When this pin is High, the device is on. When this pin is Low, the device is off. Voltage should not be applied to this pin before VCC3 is applied. Type: D, I	
13	GND_SLUG	Ground connection. The backside of the package should be soldered to a top side ground pad which is connected to the ground plane with multiple vias. The pad should have a short thermal path to the ground plane. Type: P	

Note: Where Type code is: I=Input; O=Output; A=Analog; D=Digital; P=Power

Evaluation Board Schematic

(Download [Bill of Materials](http://www.rfmd.com) from www.rfmd.com.)



NOTE:

Resistors R2 and R3 are provided on the evaluation board to protect against power sequencing issues. (Refer to pin descriptions 11 and 12.) These resistors are not needed when the VCC3 is connected to the handset battery.

RF3300-3